



Material Content Data Sheet



Sales Product Name		ICL8001G		Issued		27. September 2017		
MA#		MA001054228						
Package		PG-DSO-8-42		Weight*		81.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.247	1.53	1.53	15283	15283
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.035	0.04		432	
	non noble metal	iron	7439-89-6	0.705	0.86		8639	
wire	non noble metal	copper	7440-50-8	28.624	35.08	35.99	350764	359943
	noble metal	gold	7440-57-5	0.167	0.20	0.20	2043	2043
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1812
plastics		epoxy resin	-	4.780	5.86		58572	
	inorganic material	silicondioxide	60676-86-0	44.348	54.35	60.39	543451	603835
leadfinish	non noble metal	tin	7440-31-5	0.824	1.01	1.01	10098	10098
plating	noble metal	silver	7440-22-4	0.084	0.10	0.10	1034	1034
glue	plastics	acrylic resin	-	0.127	0.16		1553	
	noble metal	silver	7440-22-4	0.507	0.62	0.78	6211	7764
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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